ASSOCIATION CONNECTING LECTRONICS INDUSTRIES INCOMPACTING International and Pan-	C. Bannockb	ourn. Illinois. A	Il rights reserved untions.	under both	This docum level parts, t	ent is a declara	tion of the s encompass	substances es all lowe	within the r level mate	manufacture erials for wh	er listed ite hich the ma	m. Note: nufacture	if the item is an as r has engineering	sembly with lowe responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form 7 http://www.ipc.org/IPC-175x Distrib				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					als and Mfg Information				
Supplier Information															
Company name* Cor			Company unique ID			Unique ID Authority					Response Date*				
onsemi												2025-06-05			
Contact Name	ntact Name Title - Contact						Phone - Contact*				Email - Contact*				
Product-Env-Stewards Product Env			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Repre			resentative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards Product Env			nviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Item Number		Mfr Item Name			Effective Dat	e Version	1	Manufacturing Site		W	eight*	UOM	Unit Type	
	SZ1SMA	5928BT3G	ZEN SMA REG 1.5W 13V TR			2025-06-05			VN5		76	.66	mg	Each	
Manufacturing Proccess Informati	on						-						-		
Terminal Plating / Grid Array Mate	rminal Plating / Grid Array Material Terminal Base A		Alloy	J-STD-020 MSL Rating		Peak Pro	eak Process Body Temperatu		are Max Time at Peak Terr		Temperature Number of Reflow Cycles		les		
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30		second	3				
Comments															
evel 1 - maximum time at peak temperatur	e during sol	dering is 10-3	0 seconds												
for more information regarding material co	mposition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	7.0	mg	Supplier	Zinc (Zn)	7440-66-6		0.014	mg
			В	Nickel (Ni)	7440-02-0		0.0252	mg
			Supplier	Iron (Fe)	7439-89-6		0.1778	mg
			Supplier	Copper (Cu)	7440-50-8		6.7725	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0105	mg
Die	1.12	mg	Supplier	Silicon (Si)	7440-21-3		1.12	mg
Die Attach Solder	3.45	mg	Supplier	Silver (Ag)	7440-22-4		0.0862	mg
			А	Lead (Pb)	7439-92-1	7a	3.1913	mg
			Supplier	Tin (Sn)	7440-31-5		0.1725	mg
Lead Frame	28.84	mg	Supplier	Zinc (Zn)	7440-66-6		0.0346	mg
			Supplier	Iron (Fe)	7439-89-6		0.6922	mg
			Supplier	Copper (Cu)	7440-50-8		28.0902	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0231	mg
Mold Compound-Black	34.87	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		3.487	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1743	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		5.0561	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		22.6655	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.487	mg
Plating	1.38	mg	Supplier	Tin (Sn)	7440-31-5		1.38	mg